



گروه فنی مهندسی جوش و برش مقدم

اعتماد از شما کیفیت و تخصص از ما



09153223758



051-37581400



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مشهد خیام شمالی 63 خیابان پردیس 3

برای کسب اطلاعات بیشتر بر روی لینک ها کلیک کنید

- 7 سال سابقه آموزش تعمیرات تخصصی دستگاه های جوش اینورتری تک فاز و 3 فاز
- 7 سال سابقه فروش قطعات الکترونیکی دستگاه جوش تک فاز و 3 فاز
- آموزش تخصصی تحلیل دستگاه های جوش اینورتری مختص ابراز فروشان
- آموزش تخصصی ابراز آلات شارژی

BC556B, BC557A, B, C, BC558B

Amplifier Transistors

PNP Silicon

Features

- Pb-Free Packages are Available*

<http://onsemi.com>

COLLECTOR 1

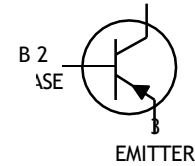
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	-65 -45 -30	Vdc
Collector - Base Voltage	V_{CBO}	-80 -50 -30	Vdc
Emitter - Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current - Continuous	I_C	-100	mAdc
- Peak	I_{CM}	-200	mAdc
Base Current - Peak	I_{BM}	-200	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

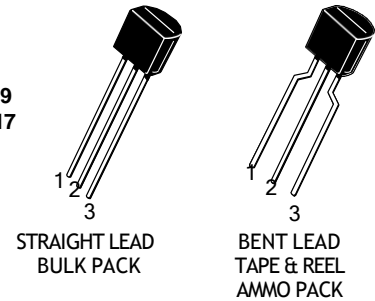
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$

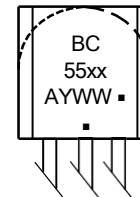
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



TO-92
CASE 29
STYLE 17



MARKING DIAGRAM



xx = 6B, 7A, 7B, 7C, or 8B
A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

BC556B, BC557A, B, C, BC558B

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit	
OFF CHARACTERISTICS						
Collector–Emitter Breakdown Voltage (I _C = –2.0 mA _{dc} , I _B = 0)	BC556 BC557 BC558	V _{(BR)CEO}	–65 –45 –30	– – –	– – –	V
Collector–Base Breakdown Voltage (I _C = –100 μA _{dc})	BC556 BC557 BC558	V _{(BR)CBO}	–80 –50 –30	– – –	– – –	V
Emitter–Base Breakdown Voltage (I _E = –100 μA _{dc} , I _C = 0)	BC556 BC557 BC558	V _{(BR)EBO}	–5.0 –5.0 –5.0	– – –	– – –	V
Collector–Emitter Leakage Current (V _{CE} = –40 V) (V _{CE} = –20 V) (V _{CE} = –20 V, T _A = 125°C)	BC556 BC557 BC558 BC556 BC557 BC558	I _{CE}	– – – – – –	–2.0 –2.0 –2.0 – – –	–100 –100 –100 –4.0 –4.0 –4.0	nA μA

ON CHARACTERISTICS

DC Current Gain (I _C = –10 μA _{dc} , V _{CE} = –5.0 V)	A Series Device B Series Devices C Series Devices	h _{FE}	– – –	90 150 270	– – –	–
(I _C = –2.0 mA _{dc} , V _{CE} = –5.0 V)	BC557 A Series Device B Series Devices C Series Devices		120 120 180 420	– 170 290 500	800 220 460 800	
(I _C = –100 mA _{dc} , V _{CE} = –5.0 V)	A Series Device B Series Devices C Series Devices		– – –	120 180 300	– – –	
Collector–Emitter Saturation Voltage (I _C = –10 mA _{dc} , I _B = –0.5 mA _{dc}) (I _C = –10 mA _{dc} , I _B = see Note 1) (I _C = –100 mA _{dc} , I _B = –5.0 mA _{dc})		V _{CE(sat)}	– – –	–0.075 –0.3 –0.25	–0.3 –0.6 –0.65	V
Base–Emitter Saturation Voltage (I _C = –10 mA _{dc} , I _B = –0.5 mA _{dc}) (I _C = –100 mA _{dc} , I _B = –5.0 mA _{dc})		V _{BE(sat)}	– –	–0.7 –1.0	– –	V
Base–Emitter On Voltage (I _C = –2.0 mA _{dc} , V _{CE} = –5.0 V _{dc}) (I _C = –10 mA _{dc} , V _{CE} = –5.0 V _{dc})		V _{BE(on)}	–0.55 –	–0.62 –0.7	–0.7 –0.82	V

SMALL-SIGNAL CHARACTERISTICS

Current–Gain–Bandwidth Product (I _C = –10 mA, V _{CE} = –5.0 V, f = 100 MHz)	BC556 BC557 BC558	f _T	– – –	280 320 360	– – –	MHz
Output Capacitance (V _{CB} = –10 V, I _C = 0, f = 1.0 MHz)		C _{ob}	–	3.0	6.0	pF
Noise Figure (I _C = –0.2 mA _{dc} , V _{CE} = –5.0 V, R _S = 2.0 kΩ, f = 1.0 kHz, Δf = 200 Hz)	BC556 BC557 BC558	NF	– – –	2.0 2.0 2.0	10 10 10	dB
Small–Signal Current Gain (I _C = –2.0 mA _{dc} , V _{CE} = 5.0 V, f = 1.0 kHz)	BC557 A Series Device B Series Devices C Series Devices	h _{fe}	125 125 240 450	– – – –	900 260 500 900	–

1. I_C = –10 mA_{dc} on the constant base current characteristics, which yields the point I_C = –11 mA_{dc}, V_{CE} = –1.0 V.

BC556B, BC557A, B, C, BC558B

BC557/BC558

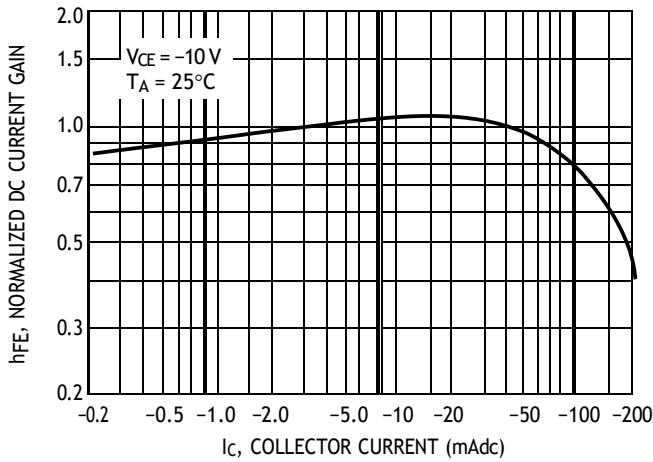


Figure 1. Normalized DC Current Gain

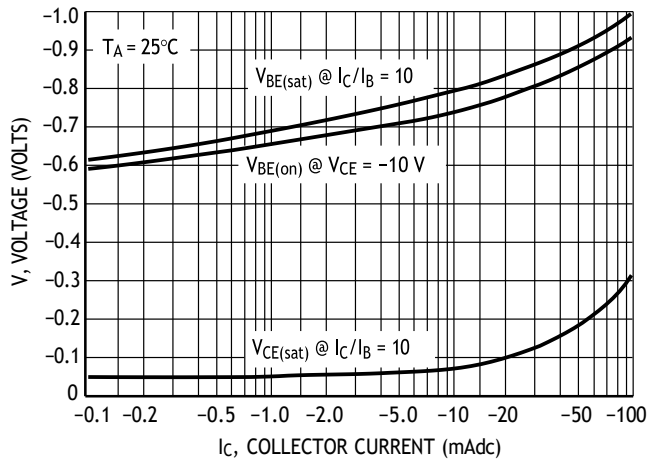


Figure 2. "Saturation" and "On" Voltages

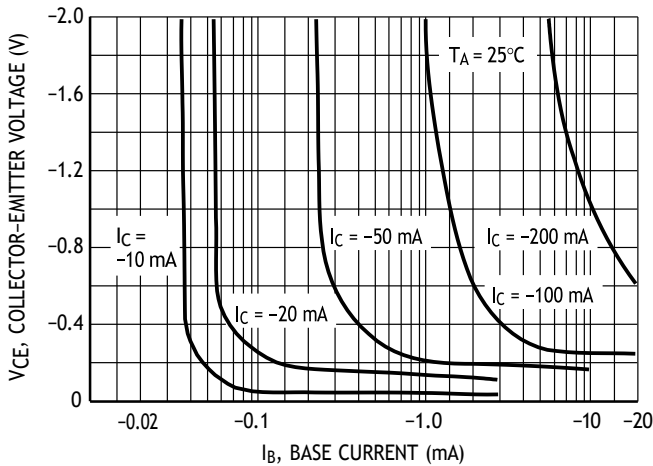


Figure 3. Collector Saturation Region

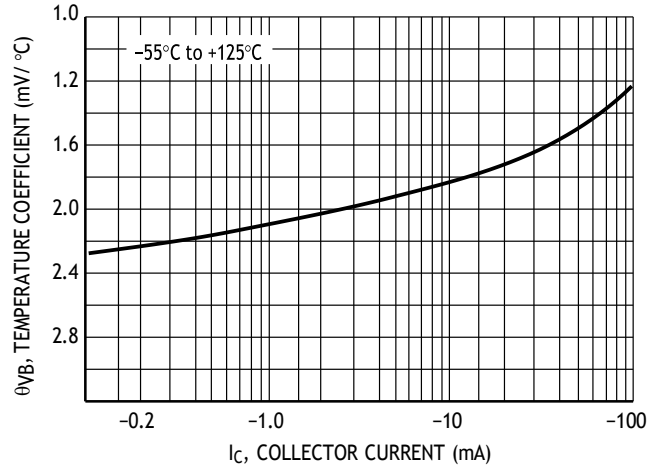


Figure 4. Base-Emitter Temperature Coefficient

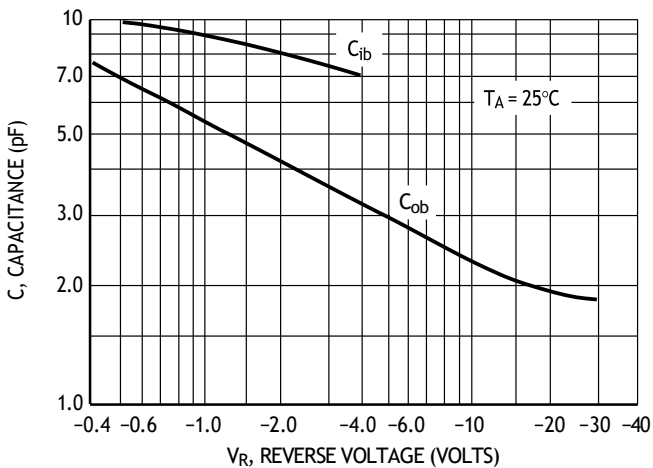


Figure 5. Capacitances

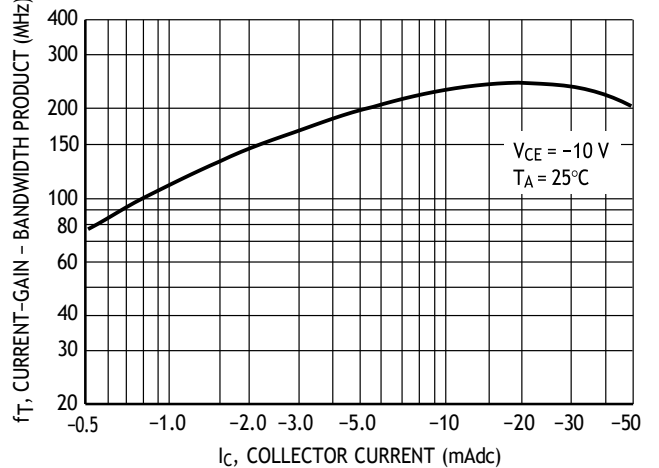
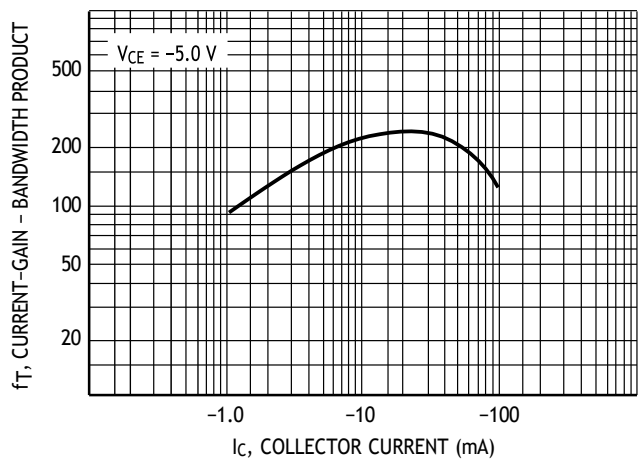
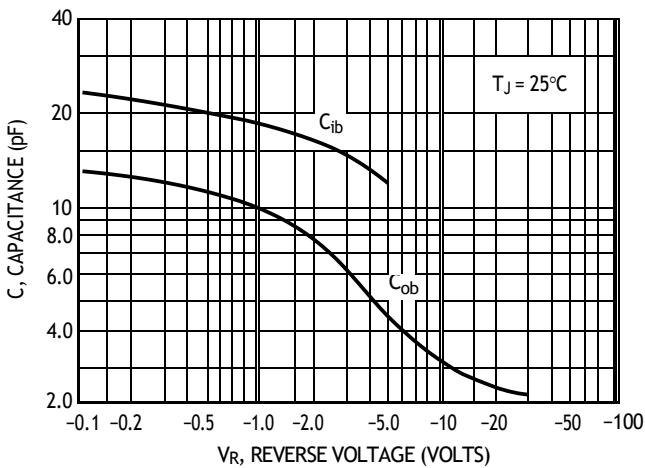
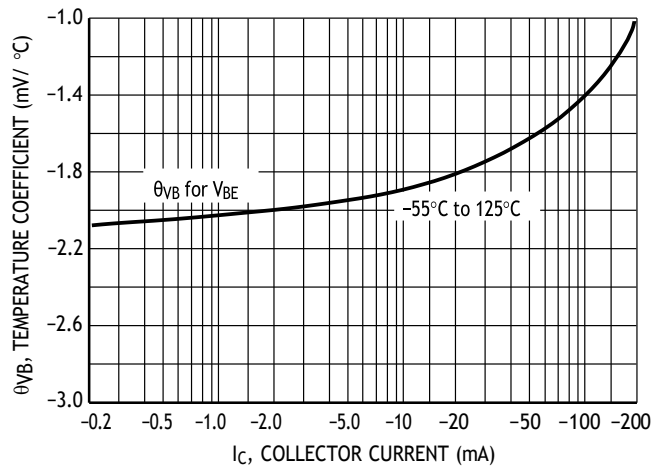
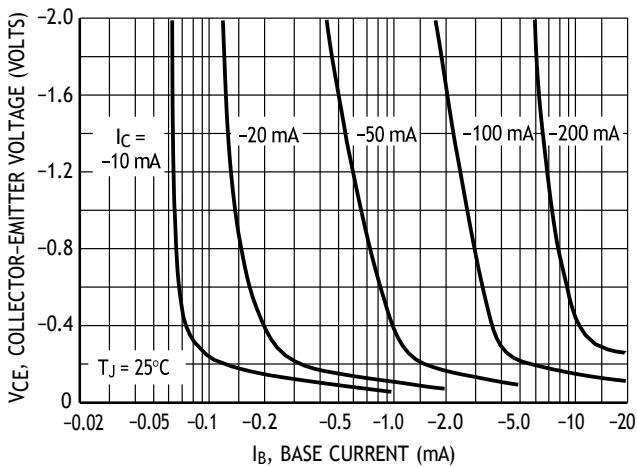
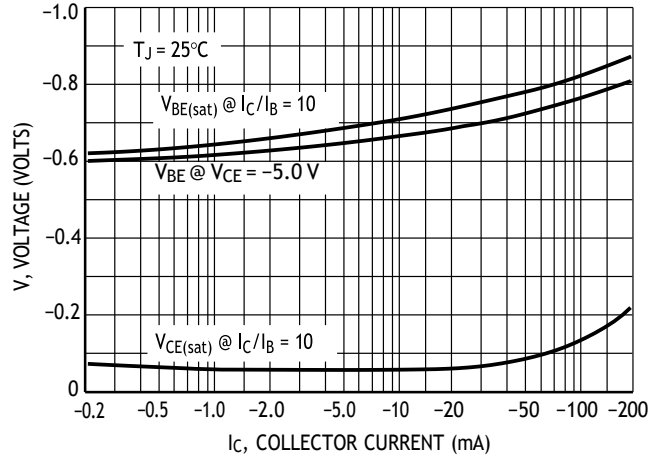
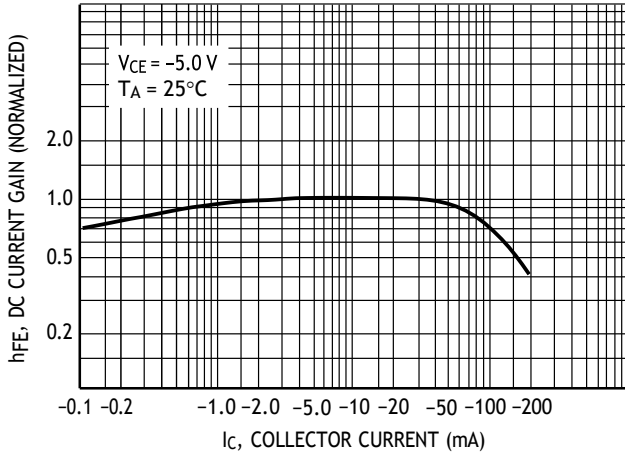


Figure 6. Current-Gain - Bandwidth Product

BC556B, BC557A, B, C, BC558B

BC556



BC556B, BC557A, B, C, BC558B

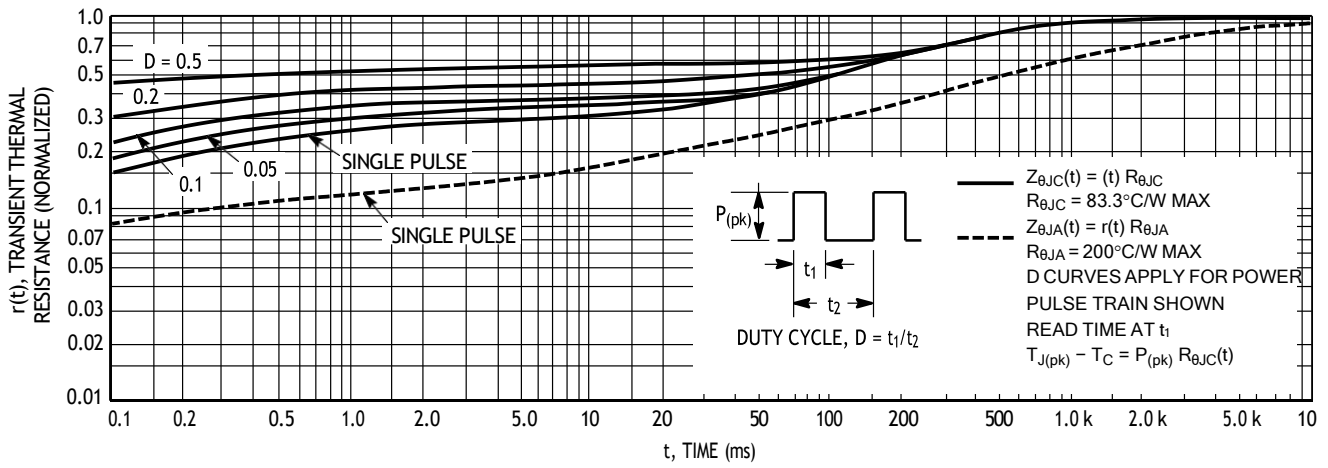


Figure 13. Thermal Response

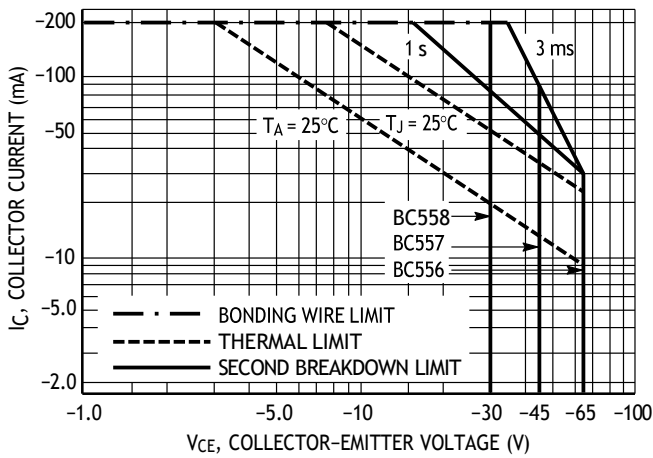


Figure 14. Active Region - Safe Operating Area

The safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 14 is based upon $T_{J(pk)} = 150^\circ\text{C}$; T_C or T_A is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 13. At high case or ambient temperatures, thermal limitations will reduce the power than can be handled to values less than the limitations imposed by second breakdown.

BC556B, BC557A, B, C, BC558B

ORDERING INFORMATION

Device	Package	Shipping†
BC556BG	TO-92 (Pb-Free)	5000 Units / Bulk
BC556BZL1G	TO-92 (Pb-Free)	2000 / Ammo Box
BC557AZL1G	TO-92 (Pb-Free)	2000 / Ammo Box
BC557BG	TO-92 (Pb-Free)	5000 Units / Bulk
BC557BRL1	TO-92	2000 / Tape & Reel
BC557BRL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
BC557BZL1G	TO-92 (Pb-Free)	2000 / Ammo Box
BC557CG	TO-92 (Pb-Free)	5000 Units / Bulk
BC557CZL1G	TO-92 (Pb-Free)	2000 / Ammo Box
BC558BRLG	TO-92 (Pb-Free)	2000 / Tape & Reel
BC558BRL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
BC558BZL1G	TO-92 (Pb-Free)	2000 / Ammo Box

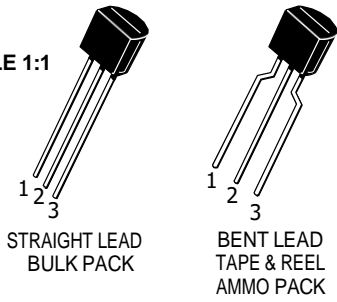
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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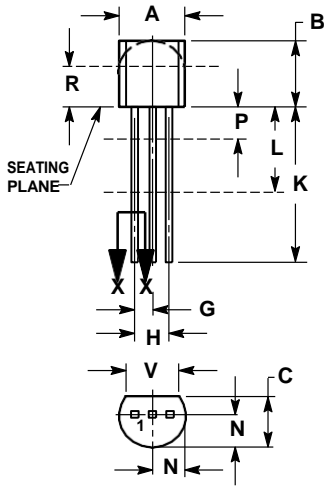


SCALE 1:1

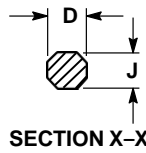


TO-92 (TO-226)
CASE 29-11
ISSUE AM

DATE 09 MAR 2007



STRAIGHT LEAD
BULK PACK

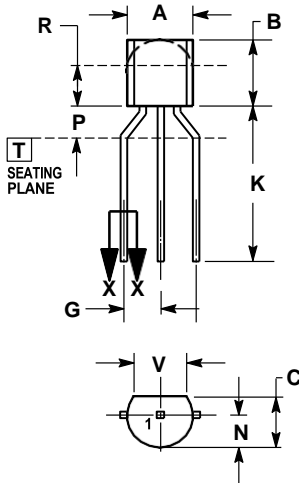


SECTION X-X

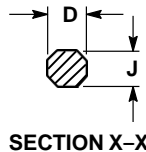
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.018	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X-X

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLES ON PAGE 2

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**TO-92 (TO-226)
CASE 29-11
ISSUE AM**

DATE 09 MAR 2007

STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 3:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 5:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 6:
PIN 1. GATE
2. SOURCE & SUBSTRATE
3. DRAIN

STYLE 7:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 8:
PIN 1. DRAIN
2. GATE
3. SOURCE & SUBSTRATE

STYLE 9:
PIN 1. BASE 1
2. EMITTER
3. BASE 2

STYLE 10:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 11:
PIN 1. ANODE
2. CATHODE & ANODE
3. CATHODE

STYLE 12:
PIN 1. MAIN TERMINAL 1
2. GATE
3. MAIN TERMINAL 2

STYLE 13:
PIN 1. ANODE 1
2. GATE
3. CATHODE 2

STYLE 14:
PIN 1. EMITTER
2. COLLECTOR
3. BASE

STYLE 15:
PIN 1. ANODE 1
2. CATHODE
3. ANODE 2

STYLE 16:
PIN 1. ANODE
2. GATE
3. CATHODE

STYLE 17:
PIN 1. COLLECTOR
2. BASE
3. EMITTER

STYLE 18:
PIN 1. ANODE
2. CATHODE
3. NOT CONNECTED

STYLE 19:
PIN 1. GATE
2. ANODE
3. CATHODE

STYLE 20:
PIN 1. NOT CONNECTED
2. CATHODE
3. ANODE

STYLE 21:
PIN 1. COLLECTOR
2. EMITTER
3. BASE

STYLE 22:
PIN 1. SOURCE
2. GATE
3. DRAIN

STYLE 23:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 24:
PIN 1. EMITTER
2. COLLECTOR/ANODE
3. CATHODE

STYLE 25:
PIN 1. MT 1
2. GATE
3. MT 2

STYLE 26:
PIN 1. V_{CC}
2. GROUND 2
3. OUTPUT

STYLE 27:
PIN 1. MT
2. SUBSTRATE
3. MT

STYLE 28:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 29:
PIN 1. NOT CONNECTED
2. ANODE
3. CATHODE

STYLE 30:
PIN 1. DRAIN
2. GATE
3. SOURCE

STYLE 31:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 32:
PIN 1. BASE
2. COLLECTOR
3. EMITTER

STYLE 33:
PIN 1. RETURN
2. INPUT
3. OUTPUT

STYLE 34:
PIN 1. INPUT
2. GROUND
3. LOGIC

STYLE 35:
PIN 1. GATE
2. COLLECTOR
3. EMITTER

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